TTM Technologies™

Analyst Day 2026

MAY 27, 2026

Analyst Day 2026: Introduction

MAY 27, 2026

Sean Hannan

DISCLAIMERS

Forward-Looking Statements

This presentation contains "forward-looking statements" within the meaning of the Private Securities Litigation Reform Act of 1995, including, but not limited to, statements related to the future business outlook, the proposed consummation of the refinancing transactions described in this presentation, the expected performance of TTM Technologies, Inc. ("TTM", "we" or the "Company") and other future events. Actual results may differ materially from these forward-looking statements. Such statements relate to a variety of matters, including but not limited to the operations of TTM's businesses and the anticipated closing of the refinancing transactions. These statements reflect the current beliefs, expectations and assumptions of the management of TTM, and we believe such statements to have a reasonable basis.

It is uncertain whether any of the events anticipated by the forward-looking statements will transpire or occur, or if any of them do, what impact they will have on the results of operations and financial condition of the Company. These forward-looking statements are based on assumptions that may not materialize, and involve certain risks and uncertainties, many of which are beyond our control, that could cause actual events or performance to differ materially from those indicated in such forward-looking statements. Factors, risks, trends, and uncertainties that could cause actual results to differ materially from those projected, anticipated, or implied in forward-looking statements include, but are not limited to potential changes in domestic or global economic conditions, demand for our products, market pressures on prices of our products, warranty claims, changes in product mix, contemplated significant capital expenditures and related financing requirements, our dependence upon a small number of customers, and other factors set forth in the Company's most recent Annual Report on Form 10-K and Quarterly Report on Form 10-Q and in the Company's other filings filed with the Securities and Exchange Commission (the "SEC"), including under the heading "Risk Factors", and which are available at the SEC's website at www.sec.gov.

TTM does not undertake any obligation to update any of these statements to reflect any new information, subsequent events or circumstances, or otherwise, except as may be required by law, even if experience or future changes make it clear that any projected results expressed in this communication or future communications to stockholders, press releases or Company statements will not be realized. In addition, the inclusion of any statement in this communication does not constitute an admission by us that the events or circumstances described in such statement are material.

Use of Non-GAAP Financial Measures

In addition to the financial statements presented in accordance with U.S. generally accepted accounting principles ("GAAP"), TTM uses certain non-GAAP financial measures, including Adjusted EBITDA, Adjusted EBITDA Margin, Non-GAAP Operating Income, Non-GAAP Net Income, Non-GAAP Operating Margin, Non-GAAP Gross Margin, Non-GAAP EPS and Free Cash Flow. We present non-GAAP financial information to enable investors to see TTM through the eyes of management and to provide better insight into our ongoing financial performance.

A material limitation associated with the use of the above non-GAAP financial measures is that they have no standardized measurement prescribed by GAAP and may not be comparable to similar non-GAAP financial measures used by other companies. We compensate for these limitations by providing full disclosure of each non-GAAP financial measure and reconciliation to the most directly comparable GAAP financial measure. However, the non-GAAP financial measures should not be considered in isolation from, or as a substitute for, financial information prepared in accordance with GAAP.

See Appendix for reconciliations of non-GAAP financial metrics to the most comparable GAAP metric. With respect to the Company's fiscal year 2026 outlook for Non-GAAP Operating Margin and Adjusted EBITDA Margin, the Company is unable to predict with reasonable certainty or without unreasonable effort certain items that may affect a comparable measure calculated and presented in accordance with GAAP. The Company's expected Non-GAAP Operating Margin excludes primarily the future impact of restructuring actions, impairment charges, and stock-based compensation. The Company's expected Adjusted EBITDA Margin excludes primarily the future impact of restructuring actions, impairment charges, unusual gains and losses including but not limited to unrealized foreign exchange translation, stock-based compensation and tax adjustments. These reconciling items are highly variable and difficult to predict due to various factors outside of management's control and could have a material impact on the most comparable U.S. GAAP financial measures for future periods. Accordingly, the Company has not provided the most directly comparable GAAP financial measure, or a quantitative reconciliation thereto, for its expected fiscal year 2026 Non-GAAP Operating Margin and Adjusted EBITDA Margin because TTM is unable to provide such reconciliation without unreasonable effort. For the same reasons, TTM is unable to address the probable significance of the information.

Data Used in This Presentation

Due to rounding, numbers presented throughout this and other documents may not add up precisely to the totals provided and percentages may not precisely reflect the absolute figures.

Third Party Information

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AGENDA

- (8:30-8:40) **Introduction** *Sean Hannan (VP, Investor Relations)*
- (8:40-9:00) **TTM Overview, Strategy & Opportunities** *Edwin Roks (President & CEO)*
- (9:00-9:45) **Aerospace & Defense Sector** *Cathie Gridley (EVP & President)*
- (9:45-10:00) **A&D Spotlight: Integrated Electronics** *Greg Fortier (SVP & President)*

BREAK

- (10:30-11:15) **Commercial Sector** *Doug Soder (EVP & President)*
- (11:15-11:30) **Commercial Spotlight: Data Centers** *Rob Farrell (SVP & President)*
- (11:30-11:45) **Financial Viewpoints** *Dan Boehle (EVP & CFO)*
- (11:45-12:15) **Audience Questions**

Analyst Day 2026: TTM Overview

MAY 27, 2026

Edwin Roks

A BRAND EVOLUTION

A MODERN NEW LOOK FOR TTM

Outgoing Logo:

Logo Evolution:

Standalone Icon:

AT-A-GLANCE

$2.9B
2025 REVENUE

19,000+
EMPLOYEES WORLDWIDE

25
GLOBAL FACILITIES

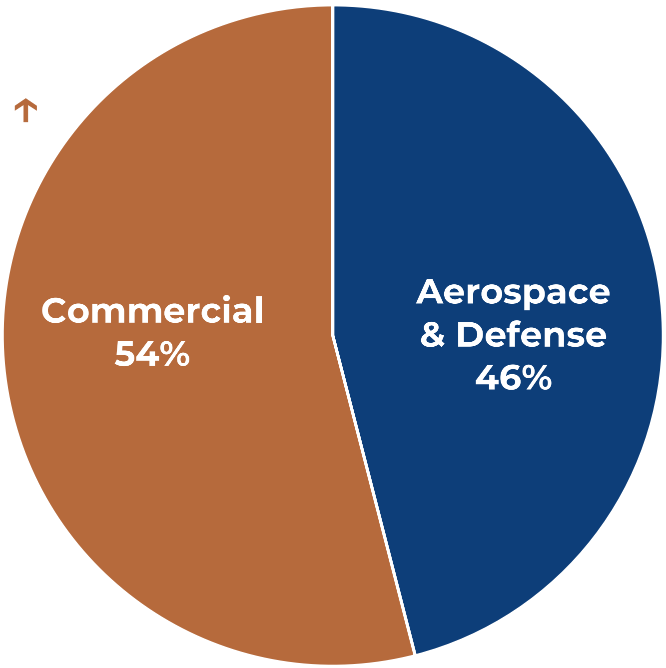
1,800+
ENGINEERS & TECH PROFESSIONALS

- Global sensing, interconnect and decision support **technology** company
- Capitalizing on **megatrends** (AI and Defense)
- Balanced portfolio of highly engineered **products**
- Strong understanding of our end **markets** (Data Centers & Networking, A&D, Medical, Industrial, and Automotive)
- Proven track record; consistent **performance**

THE REPORTING SEGMENTS

Total 2025 Revenue $2.9B
19% YoY Growth

- Data Center & Networking ↑ ↑
- Medical ↑
- Instrumentation ↑
- Industrial ↑
- Automotive ↓



- Defense ↑
- Aerospace & Unmanned ↑
- Space ↑

All numbers include RF&S.

A WINNING STRATEGY

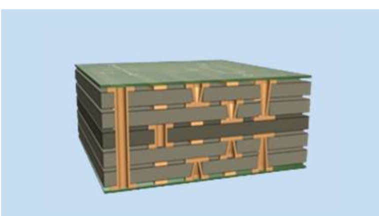
Interconnect Solutions

The nervous system, connecting the "brains", extending Moore's law

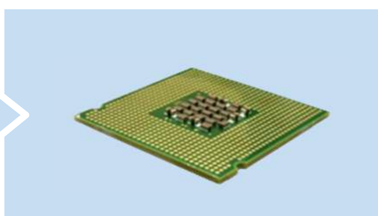
- Printed Circuit Boards
- Substrates/Interposers
- Heterogeneous Packaging

Integrated Products

- Printed Circuit Board Assemblies
- Integrated Modules
- Sub System/Chassis with Cooling and Power
- Full System Architectures

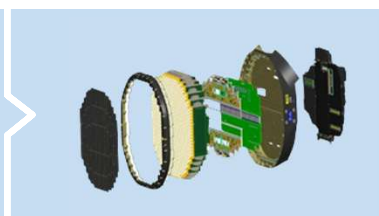


PCB



PCBA

Module



Assembly

Integration

END MARKETS

Data Center & Networking

- High Performance Computing
- Switches / Servers
- Security

Medical

- Surgical Robotics
- Patient Monitoring Devices
- Test & Diagnostics

Industrial

- Robotics
- Industrial Automation
- Humanoids

Instrumentation

- Semiconductor Test
- Memory Test
- Analytic Systems

Defense

- Surveillance Radar
- Missile Guidance & Control
- Electronic Warfare
- Threat Detection
- Unmanned

Aerospace & Unmanned

- Fixed Wing
- Rotary Wing
- Advanced Air Mobility
- Drone

Space

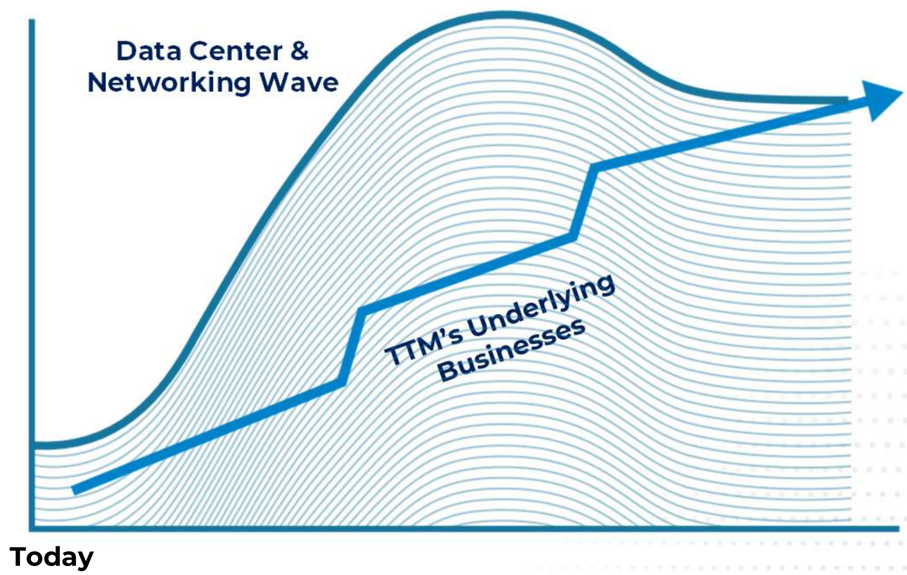
- Space Imaging
- Satellite Communications
- Rad-Hard/Tolerant Electronics
- Missile Tracking

Automotive

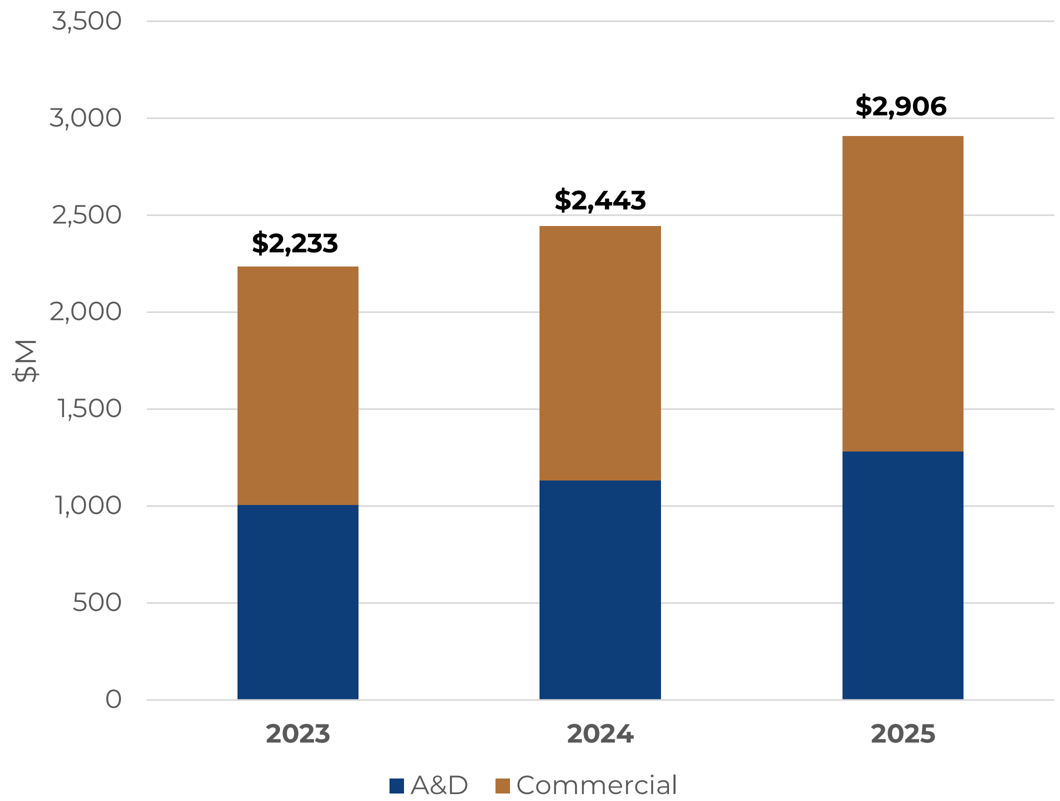
- ADAS
- Comms & Compute
- High Voltage

BALANCED AND DIVERSIFIED GROWTH

- Supporting the demand wave of **Artificial Intelligence** with our Data Center and Networking business
- Continue, above market, growth of our **Aerospace & Defense** and other Commercial businesses
- **Ready to accelerate growth** from a position of technical, operational, and financial strength

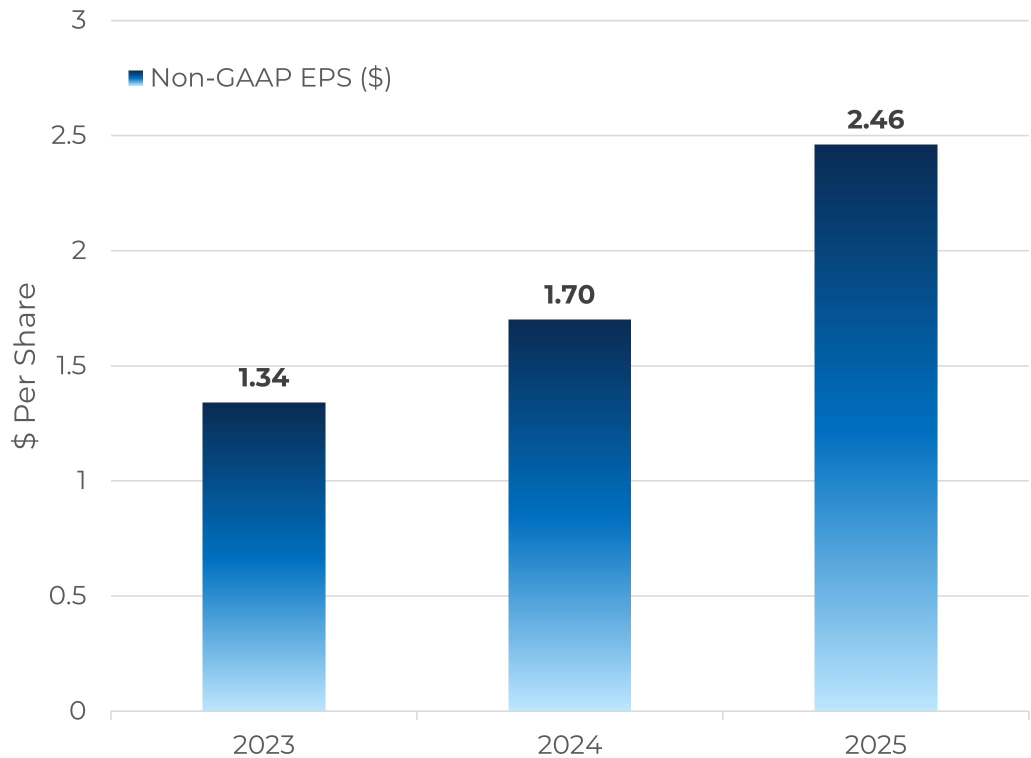


SUSTAINED REVENUE GROWTH



- Growth accelerating – 2025 year-over-year growth was 19%, while 2-year CAGR was 14%
- Momentum supported by durable end-markets & alignment to global mega trends in Aerospace and Defense and Artificial Intelligence

SUSTAINED EARNINGS GROWTH



Adjusted EBITDA Margin:	13.4%	14.4%	15.7%

- Profitable growth – margin expansion driving EPS acceleration
- Clear and progressive step-up in profitability

Non-GAAP financial measure. See Appendix for reconciliations.

CAPITAL & RESOURCE DEPLOYMENT STRATEGY

Operational Excellence

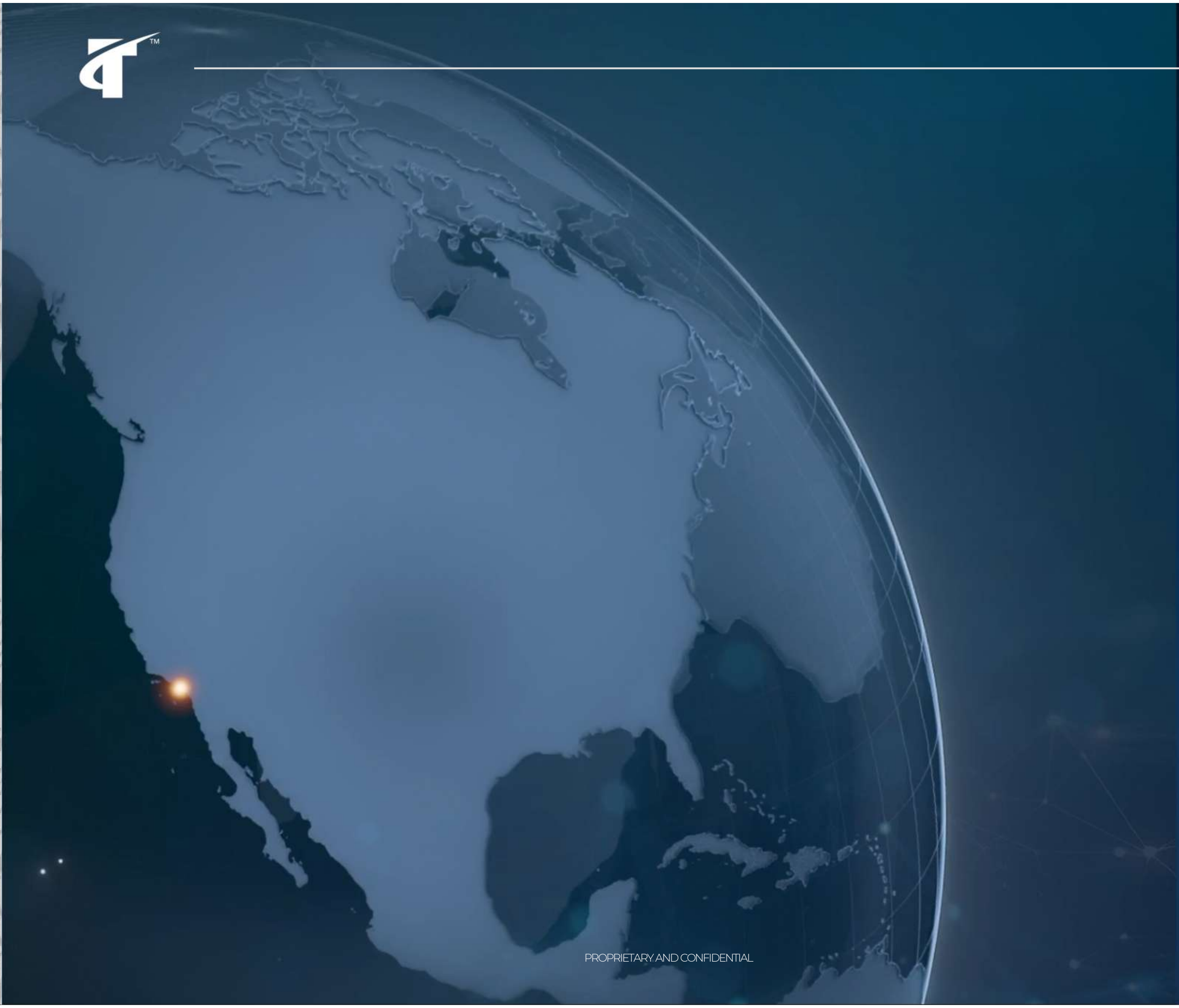
- Supply chain
- 80/20

Organic Growth

- New technology
- Capacity expansion

M&A

- Up the chain
- Global expansion
- Business diversification



A GLOBAL FOOTPRINT

AN INTERNATIONAL MANUFACTURING POWERHOUSE

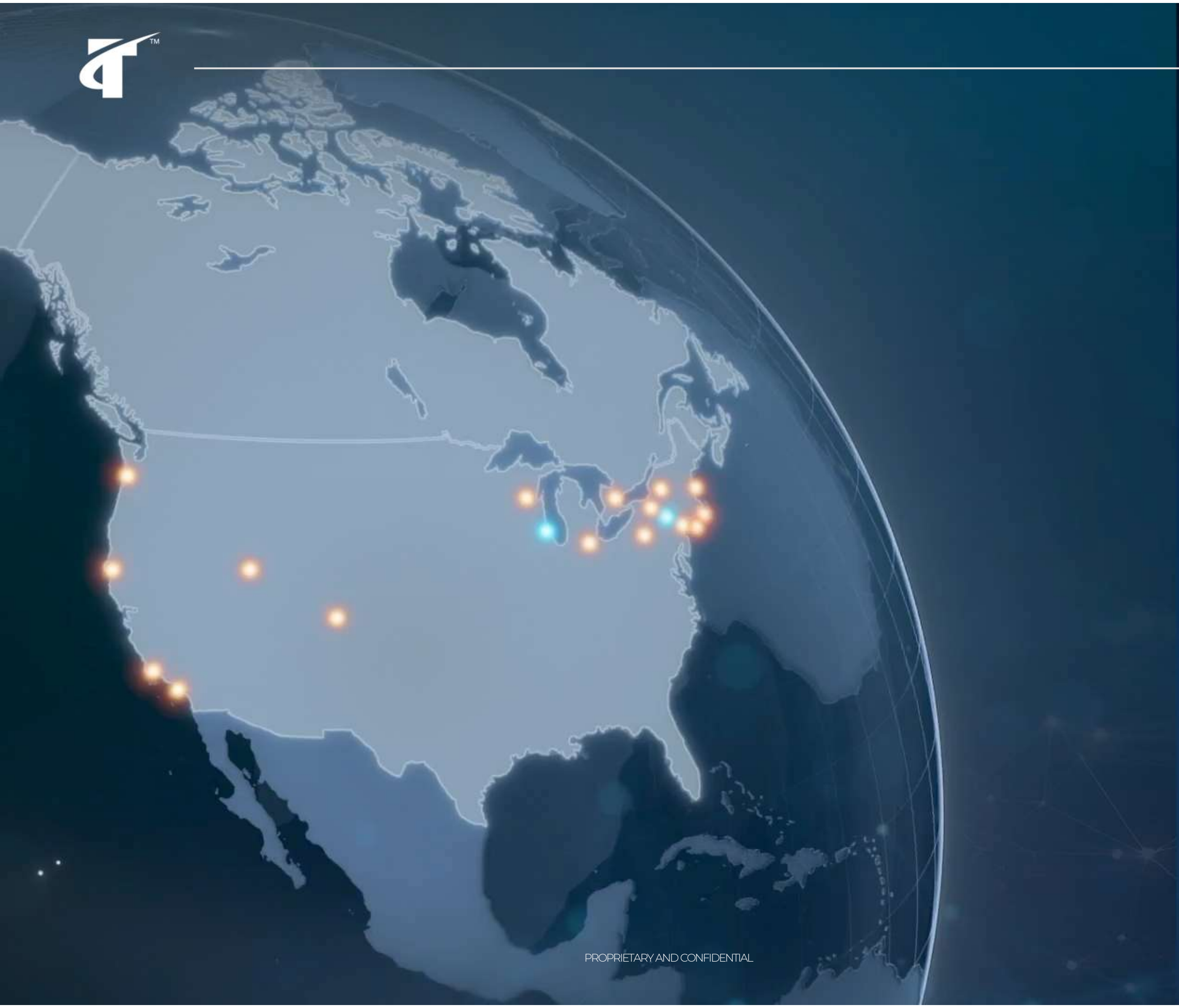
Headquartered in Santa Ana, CA

A GLOBAL FOOTPRINT

AN INTERNATIONAL MANUFACTURING POWERHOUSE

18 North America Operations

- Chippewa Falls, WI
- Denver, CO
- Farmingdale, NY
- Forest Grove, OR
- Logan, UT
- North Jackson, OH
- San Diego, CA
- San Jose, CA
- Salem, NH
- Santa Ana, CA
- Stafford, CT
- Stafford Springs, CT
- Sterling, VA
- Syracuse, NY (x2)
- Toronto, Canada
- Eau Claire, WI
- Syracuse, NY



A GLOBAL FOOTPRINT

AN INTERNATIONAL MANUFACTURING POWERHOUSE

7 Asia Pacific Operations

- Dongguan, China
- Guangzhou, China
- Huiyang, China
- Penang, Malaysia
- Suzhou, China
- Zhongshan, China
- Penang, Malaysia

A GLOBAL FOOTPRINT

AN INTERNATIONAL MANUFACTURING POWERHOUSE

On the Horizon:

Anticipated European Expansion

WHY WE WIN

CREATING SUSTAINABLE, PROFITABLE LONG-TERM GROWTH

- An advanced **technology leader**
- Capitalizing on the world’s **mega trends**
- Trusted **business relationships**
- **High barriers to entry**
- **Global** manufacturing footprint
- **Diversified** across markets, footprint, capabilities, customer base
- **Financially strong & disciplined**
- **Customized Interconnect** is our enabler for **Integration**

Analyst Day 2026: Aerospace & Defense Sector

MAY 27, 2026

Cathie Gridley

A&D AT-A-GLANCE

- Design-to-spec, highly engineered products
- Addressing Defense, Space, and Commercial Aviation end-markets
- 16 North America manufacturing locations
- Trusted customer relationships and strong Defense program alignment
- Spanning Interconnect and Integrated Electronics, including Mission Systems

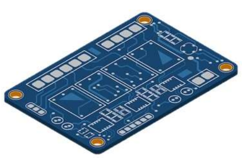
INTERCONNECT + INTEGRATION IN A&D

Interconnect Solutions

- Printed Circuit Boards
- Substrates/Interposers
- Heterogeneous Packaging

Integrated Products

- Printed Circuit Board Assemblies
- Integrated Modules
- Sub System/Chassis with Cooling and Power
- Full System Architectures



PCB

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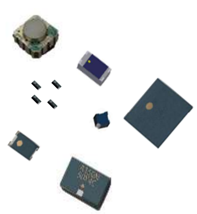

Components

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Module

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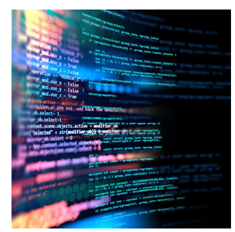

Software

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Integrated Chassis

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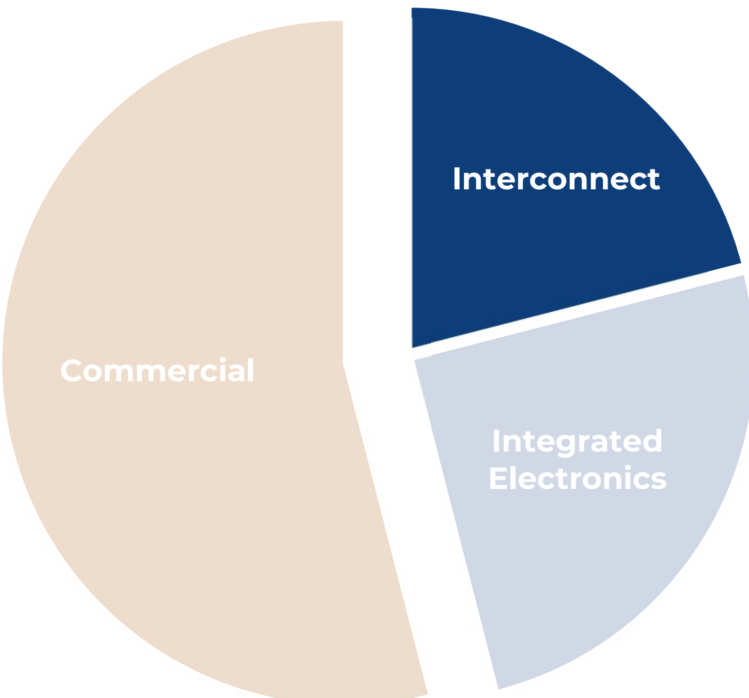
Integrated System

A&D 2025 FINANCIAL PROFILE

OUTPACING MARKET GROWTH, STRONG DEMAND SIGNALS CONTINUE



$1.3B	$221M	17.2%
REVENUE	EBITDA	EBITDA MARGIN
(+$151M / +13% YoY)	(+$40M / +22% YoY)	(+120bps YoY)

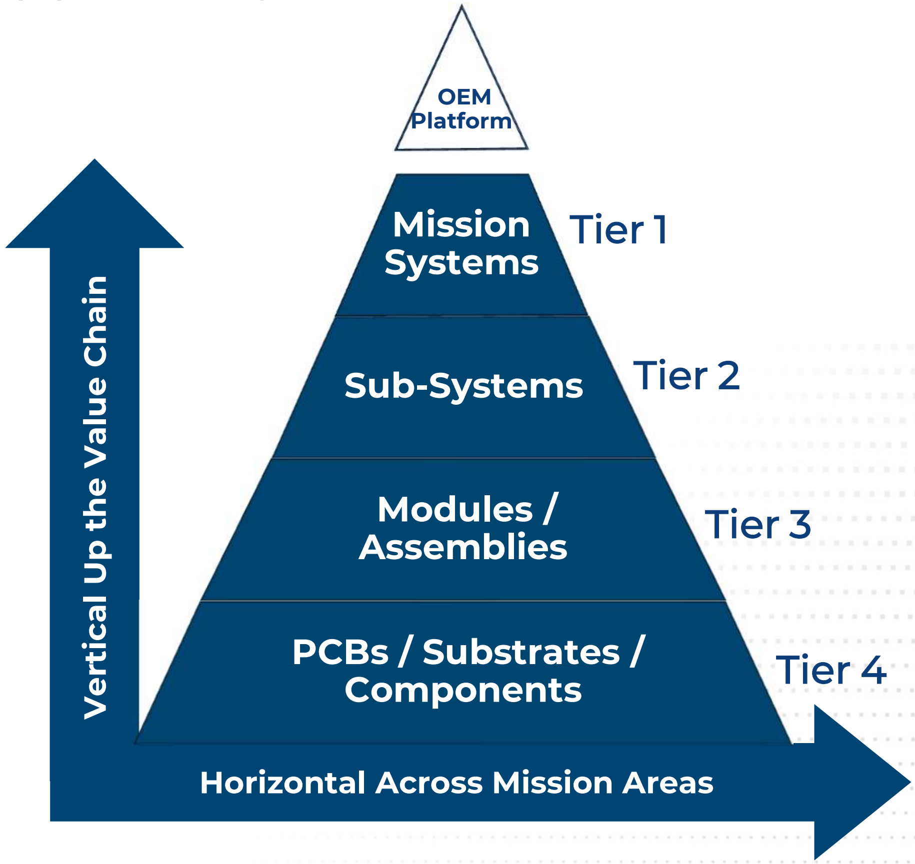
$1.35B	$1.6B	$7.2B
BOOKINGS	BACKLOG	PIPELINE
& 1.04 B:B		

*All numbers exclude RF&S.

A&D STRATEGY

DIFFERENTIATED OFFERINGS IN ALL FOUR TIERS OF THE ELECTRONICS SUPPLY CHAIN

- Expand engineering and integration expertise
- Replicate domestic market position internationally
- Accelerate investment in packaging and test capabilities
- Optimize demand across our footprint while preserving dual-source resilience
- Deepen customer engagement; engineering, programs, leadership



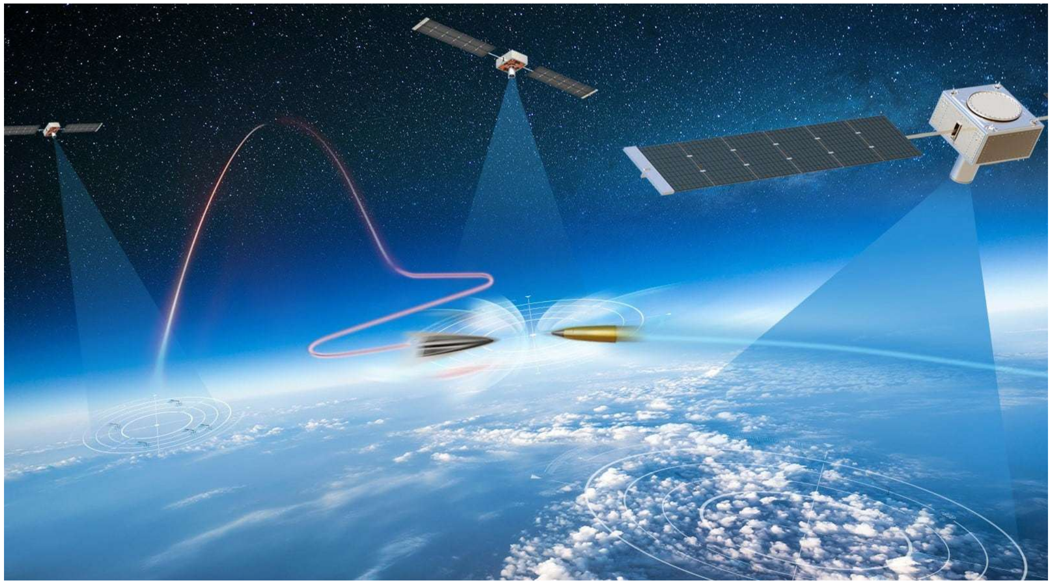
DEFENSE:
ENABLING MISSION-CRITICAL ELECTRONICS

- Autonomy/Unmanned
- Converged Sensors
- Counter UAS
- Guidance
- Surveillance

Enabling Technologies

- **Multi-Function Apertures**
- **RF Modules**
- **Direct RF Sampling (RF to Bits)**
- **Artificial Intelligence**
- **Rad Hard Multi-Chip Modules**
- **Advanced Packaging**

SPACE:
SUPPORTING DOMAIN SUPERIORITY



| Autonomous Sensing

| Communications

| Navigation

| Electromagnetic Superiority

Enabling Technologies

- Active Beamforming
- RF Modules
- Rad Tolerant Multi-Chip Modules
- Identification Friend or Foe Sensors
- Radar Sensors
- Advanced Packaging

OUR DIFFERENTIATION

THE FOUNDATION FOR CONTINUED ABOVE-MARKET GROWTH

- Vertically integrated, diverse product portfolio
- Multi-decade strategic customer and supplier relationships
- Deep history of industry-first innovations
- Operational excellence with a dual-source, multi-location footprint
- Board-to-system design capability across hardware and software
- Deep program portfolio with significant DoW installed base

INVESTMENT IN CAPACITY & CAPABILITY

- Expanding North America capacity to support A&D demand
    - Syracuse, NY: ultra high density interconnect
    - Sterling, VA: munitions acceleration
    - Chippewa Falls, WI: defense growth and PCB reshoring
    - Farmingdale, NY: system design, integration & test
- Enabling >$500 million in projected incremental throughput by 2028
- Preparing TTM for DoW munitions and weapon system acceleration and Golden Dome demand
- Bringing technical capability for U.S. manufacturing reshoring needs

New 200,000+ sq ft TTM Syracuse Facility

STRONG FRANCHISE POSITIONS

EMBEDDED IN PROGRAMS THAT MATTER

Munitions

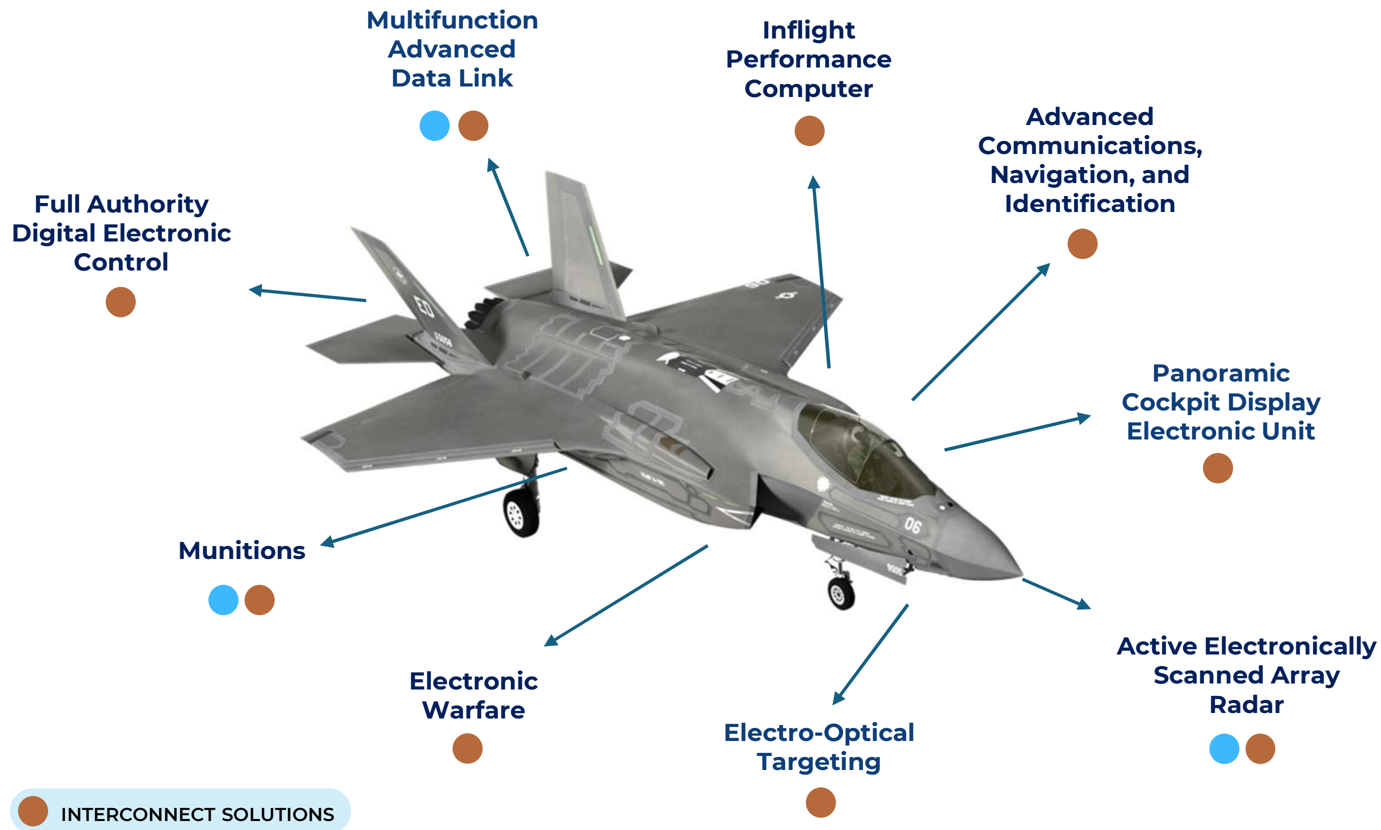
Artemis II Mission

F-35 Lightning II

- Content on over 480 Programs, 30+ munitions
  - Decades of space-hardened product experience
    - Core to a significant number of National Security programs

PROGRAM SHOWCASE: F-35

TTM CONTENT ENABLING MISSION-CRITICAL SYSTEMS



- 2,000 TTM parts per aircraft
- 7 different integrator customers
- 8 TTM sites
- Active production expected beyond 2040
- Operational life projected into the 2080s

INTERCONNECT SOLUTIONS

INTEGRATED ELECTRONICS

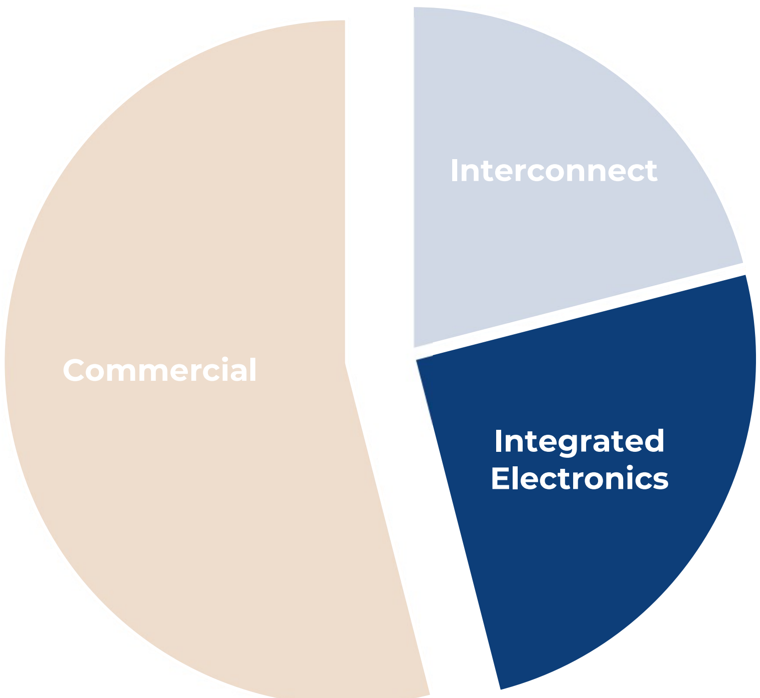
Analyst Day 2026:
A&D Spotlight – Integrated Electronics

MAY 27, 2026

Greg Fortier

INTEGRATED ELECTRONICS AT-A-GLANCE

DELIVERING THE TACTICAL ADVANTAGE



- Diverse portfolio across DoW, Foreign Military customers, Commercial Aerospace and National Security Space
- Three segments span the entire value chain:
  - Microelectronics/Microwave **components**
  - Mission Critical **subsystems**
  - Radar, Surveillance, Communications **systems**
- Leverages TTM's organic engineering design and factory capacity to **respond ahead of need**

MULTI-DOMAIN OPERATIONS

TTM GROWING IN ALL DOMAINS

Rapid and Continuous Joint Force Integration of all Domains of Warfare to Defeat Complex Adversaries

Cross-Domain Integration	Current Positions	Growth Areas
 Space	Missile Warning & Tracking Rad Hard Electronics	Space Payloads & Packaging Rad Tolerant LEO Electronics
 Air	Airborne Radar Precision Strike Identification Friend or Foe	Group 1–5 UAS Electronics Next-Gen Radar (AESA)
 Maritime	Naval Radar & Sensing Shipboard Missiles	Subsea Systems UUV Electronics
 Land	Air & Missile Defense Tactical Communications Guided Munitions	Counter UAS Systems Edge Compute for Battlefield Networks

CASE STUDY: GOLDEN DOME

A CORE ROLE IN A NEW ERA OF MULTI-LAYER MISSILE DEFENSE SYSTEMS

- TTM **embedded at every known phase** of Golden Dome instantiation
- Now through near term: **increased TTM demand** through “franchise programs”
- Medium term: growing through the **expansion of both the offensive and defensive** parts of the kill chain
- Further growth through **long-term modernization**
- Speed of delivery and product quality **remain the differentiator**

CASE STUDY: SENSE AND AVOID RADAR

POSITIONED TO CAPTURE NEW DEMAND IN ADVANCED AIR MOBILITY (AAM)

- Designing, developing, and delivering the **"Sense and Avoid" radar** for autonomous air taxi
- "Sense and Avoid" identified as **critical path to market**
- Complementary near-term applications in other markets support **long-term differentiation**
- **Radar technology transfers to the next-generation** Air Traffic Control System (BNATCS) and the **Counter-UAS** markets

A&D SECTOR - WHY WE WIN

WELL POSITIONED TO DRIVE LONG-TERM VALUE

- Aligned to priority defense and space investments and mega trends
- Trusted for mission-critical, long-duration programs
- Enabling emerging defense technology
- Technical differentiation supporting a durable competitive position
- A&D mix driving sustainable margin expansion

Analyst Day 2026

BREAK

Analyst Day 2026: Commercial Sector

MAY 27, 2026

Doug Soder

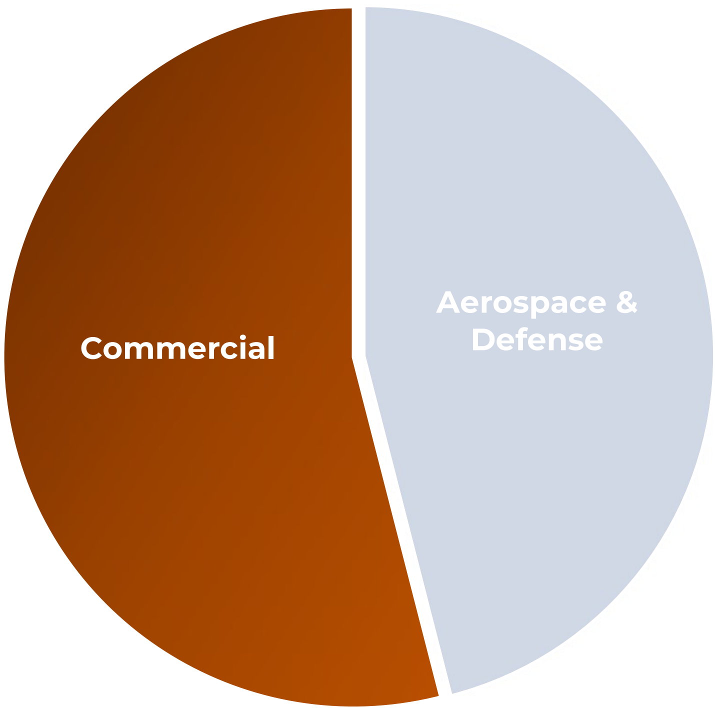
COMMERCIAL AT-A-GLANCE

- A global leader in Data Center & Networking
- #1 in Medical, Industrial, and Instrumentation*
- Targeted Automotive technology leadership
- Deep & longstanding customer relations
- Unique global footprint to serve our customers
- Only US PCB company in Global Top 5

*Measured in annual revenues

COMMERCIAL 2025 FINANCIAL PROFILE

PROFITABLE GROWTH & STRONG BOOKINGS SETS UP STRONG 2026



$1.6B
REVENUE
(+$310M / +24% YoY)

$304M
EBITDA
(+$63M / +26% YoY)

19.2%
EBITDA MARGIN
(+29bps YoY)

$1.8B
BOOKINGS
& 1.2 B:B

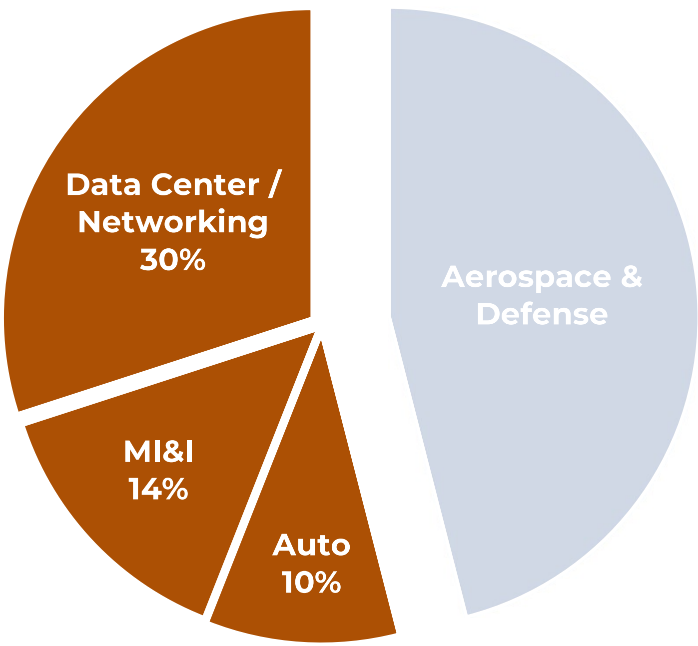
700+
OEM CUSTOMERS

All numbers exclude RF&S.

END MARKET HIGHLIGHTS

DIVERSIFIED END MARKETS PROVIDE BALANCED PLATFORM FOR PROFITABLE GROWTH

TTM Total 2025 Revenue $1.6B



Data Center / Networking ("DC/NW")

- Revenue: **$0.9B (+$250M / +40% YoY)**
- SAM Share: **9% of $9.8B Global Market**
- Focus Areas: **Switches, AI Servers, Servers**

Medical, Industrial & Instrumentation ("MI&I")

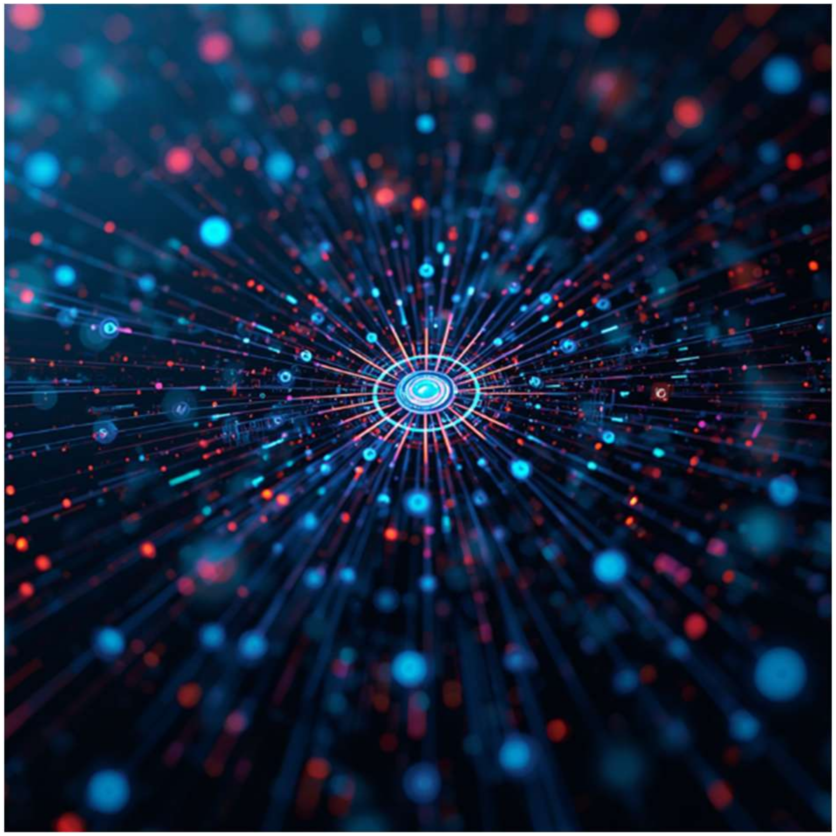
- Revenue: **$0.4B (+$73M / +22% YoY)**
- SAM Share: **18% of $2.3B Global Market**
- Focus Areas: **Patient Monitoring, Robotics, Factory Automation, Industrial Controls, Semiconductor Test**

Automotive ("Auto")

- Revenue: **$0.3B (-$13M / -4% YoY)**
- SAM Share: **4% of $7.7B Global Market**
- Focus Areas: **ADAS, Electrification**

STRATEGY

CREATING DIFFERENTIATION & MARKET OUTPERFORMANCE



- **Targeted** end market and customer engagements
- **Focused Advanced Technology Leadership**
- **Global Footprint Management** for differentiated market solutions
- **Disciplined Capacity & Capability Investments**

MEGATRENDS

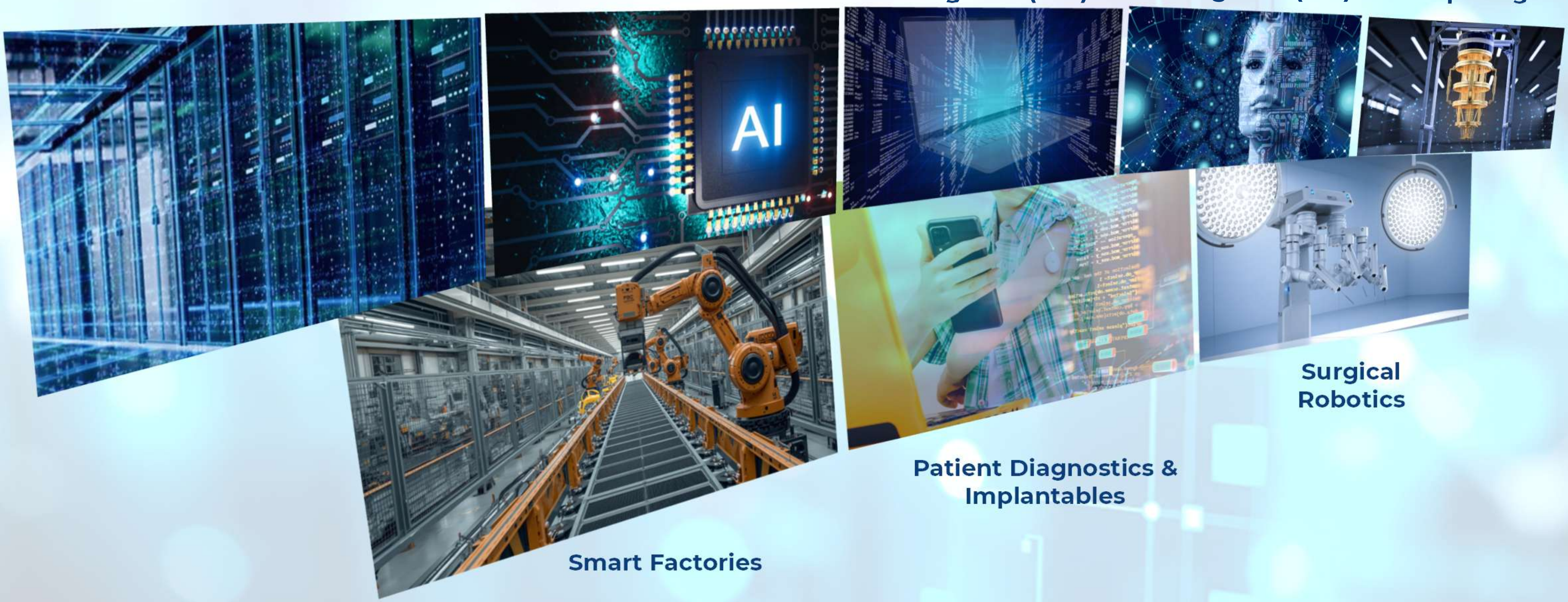
Data Center

Generative AI (GAI)

Artificial General Intelligence (AGI)

Artificial Super Intelligence (ASI)

Quantum Computing



Surgical Robotics

Patient Diagnostics & Implantables

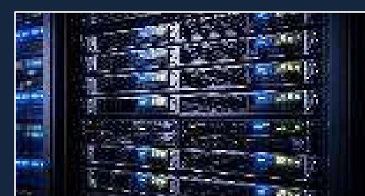
Smart Factories

DATA CENTER/NETWORKING

TTM IS A GLOBAL LEADER AND “XPU” AGNOSTIC – SUPPORTING MULTIPLE DATA CENTER ECOSYSTEMS

AI Servers

Switches



General Purpose Servers

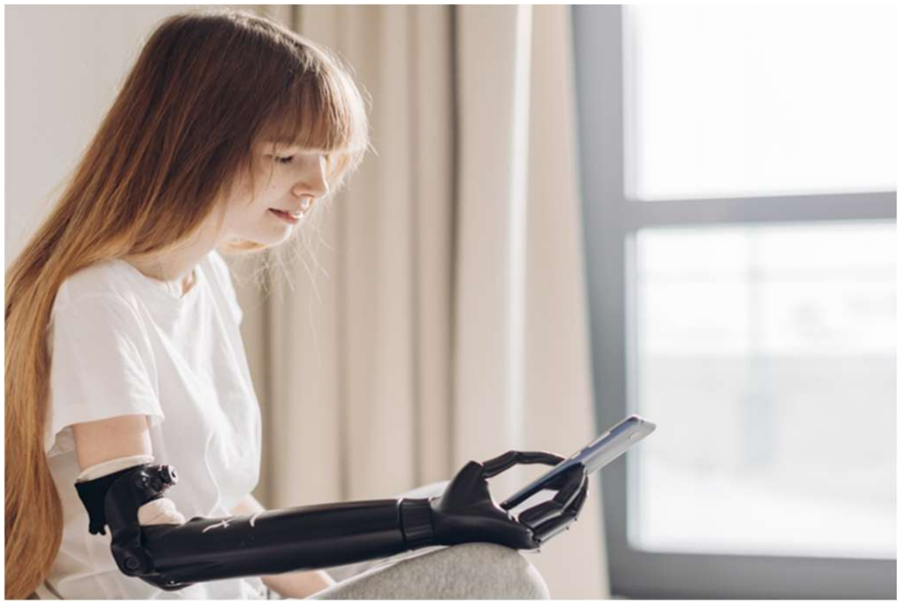
Backplane / Midplane Chassis

Enabling Technologies

- N+M PCBs (Asymmetric Architecture)
- High & Ultra High Layer Count PCBs
- HDI and Stacked Microvias (SMV)
- High Performance Materials Expertise
- Optical PCBs and Packaging
- TTM Proprietary IP Solutions

MEDICAL

TTM IS GLOBAL #1* – ENABLING STATE-OF-THE-ART MED TECH ADVANCEMENTS



Patient Monitoring

Implantable Devices

Surgical Robotics

Diagnostics

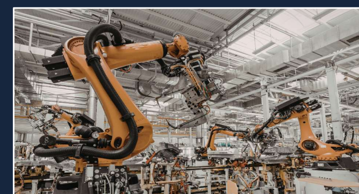
Enabling Technologies and Solutions

- **Advanced Tech PCBs & Rigid-Flex**
- **Miniature to Large Format**
- **HDI & SMV**
- **High Performance Materials Expertise**
- **TTM Proprietary IP Solutions**
- **Focused High Mix Factories**

**Measured in annual revenues*

INDUSTRIAL & INSTRUMENTATION

TTM IS GLOBAL #1* – SUPPORTING TECHNOLOGY INNOVATION ACROSS DIVERSE I&I CUSTOMERS



Industrial Automation / Robotics

Network Analyzer

Semiconductor Test

Oil & Gas Controls

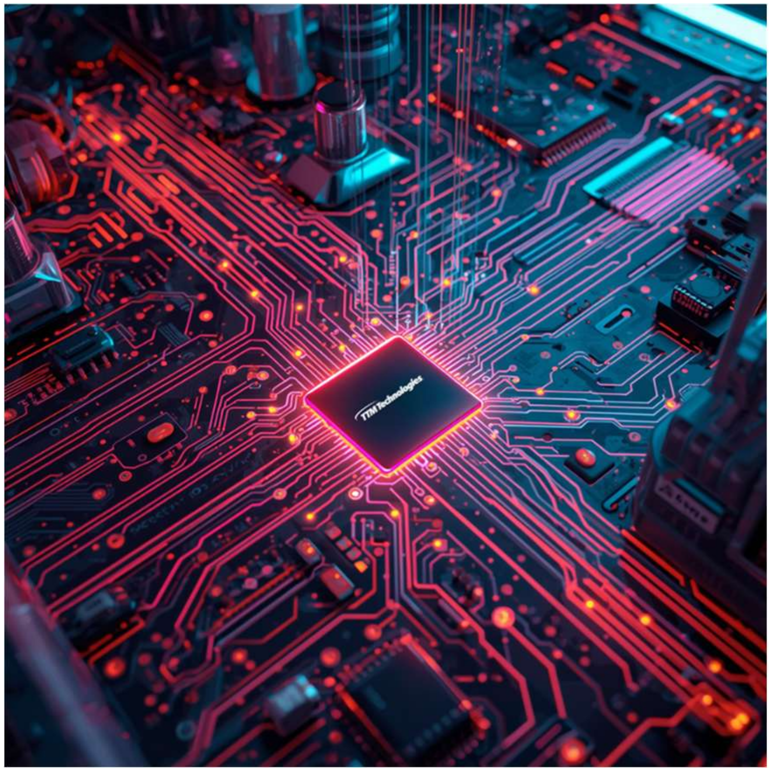
Enabling Technologies

- **Advanced Tech PCBs and Rigid-Flex**
- **High & Ultra High Layer PCBs**
- **HDI & SMV**
- **High Performance Materials Expertise**
- **TTM Proprietary IP Solutions**
- **Focused High Mix Factories**

*Measured in annual revenues

CUSTOMER-FOCUSED TECHNOLOGY DEVELOPMENT

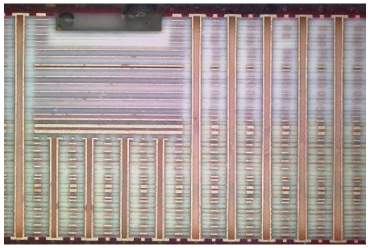
EARLY COLLABORATION FOR FOCUSED TECHNOLOGY LEADERSHIP POSITIONS



- **Global Technology Solutions Organization**
- **Technology Labs & Innovation Center**
- **Advanced Testing & Analytics for Process & Product Development**
- **Prototyping and NPI**
- **Interconnect & Integration Outcomes Include:**
  1. Asymmetric N+M PCBs
  2. Ultra High Layer Count PCBs
  3. Optical Interconnect & Packaging Development
  4. CoWoP Development

TECHNOLOGY DEVELOPMENT ROADMAP

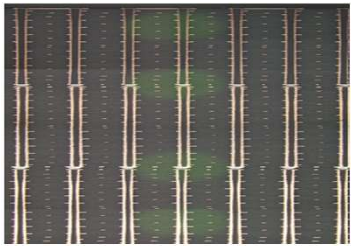
N+M Asymmetric PCBs



Production: Now

1

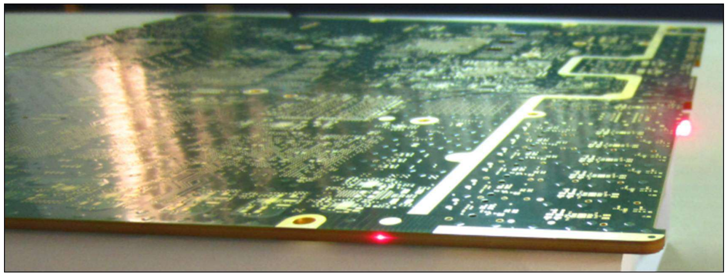
Ultra High Layer Midplanes & Backplanes



Production: 1-2 Years Out

2

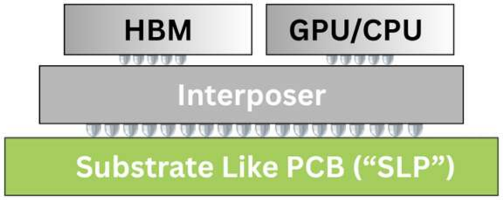
Optical PCBs & Packaging Solutions



Under Development

3

Advanced Packaging Development (CoWoP)

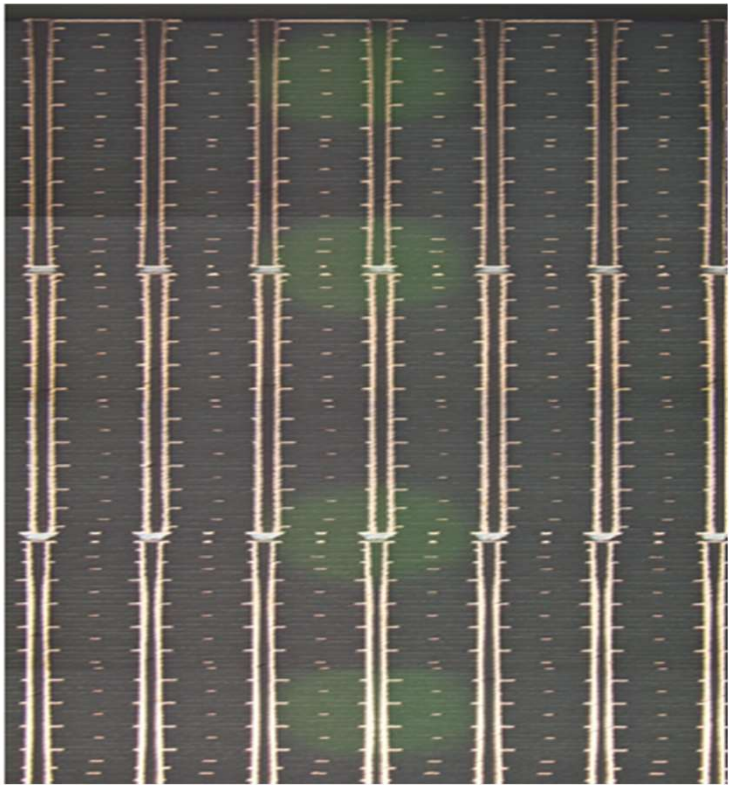


Under Development

4

NEW PRODUCT TECHNOLOGY EXAMPLE

ULTRA HIGH LAYER COUNT BACKPLANES AND MIDPLANES



Key Attributes

- Large format midplanes & backplanes
- Up to 150 layers
- Advanced materials for signal integrity
- Sintered conductive paste to connect sub-sections

Customer Benefits

- Improved reliability & packaging
- Total cost of ownership

GLOBAL FOOTPRINT MANAGEMENT

$1 BILLION INVESTED; APPROPRIATE SCALE-UP AND CAPEX TO REVENUE CONVERSION SOLUTIONS

United States/Canada

- Toronto, Logan & San Jose: QTA, NPI, High Mix Production
- Eau Claire: Will Be Largest US Advanced Interconnect Plant

China

- Dongguan & Guangzhou: N+M, Advanced Tech PCBs
- Huiyang: High Mix Production, Advanced Tech PCBs
- Zhongshan: Auto Specialty; Non-Auto Advanced Tech PCBs

Southeast Asia – China+

- Penang: High Tech PCBs
- Penang 2: Next Step; Advanced Tech PCBs

NOT THE MATRIX...

TTM PENANG: STATE-OF-THE-ART, HIGHLY AUTOMATED FACTORY

THE N+M SCALE-UP

TECHNOLOGY DEVELOPMENT + GLOBAL FOOTPRINT EXECUTION

$450M
CAPITAL INVESTMENTS
From 2025-27 to increase N+M capacity

APPROX. **$4.5B**
EST. REVENUE OPPORTUNITY
Customers across multiple Data Center ecosystems adopting N+M high layer PCBs

2025-26
$300M
FACILITY EXPANSIONS & EQUIPMENT INVESTMENTS
To support N+M development and mass production ramp

2027
$150M
PLANNED CAPEX
For capacity expansion in 2027

DMC2 – May 2026 (270 Drills)
2 Months for 2x Drill Capacity (DMC)

CUSTOMER SUCCESS STORIES

TECHNOLOGY LEADERSHIP & DIFFERENTIATION HELPS TTM'S CUSTOMERS WIN

Surgical Robotics ~ 75% Market Share

Early engagement & global footprint management = Competitive Advantage

- Engineering Partnership
- Coordinated 4 TTM site Customer support
- Prototype, NPI and mass production
- Quick-turn service in production facilities shortens qualification and FDA approvals

Glucose Monitoring ~ 75% Market Share

18+ years partnership – Product development and multi-plant production solutions

- 300M+ devices shipped
- Quick-turn service in production facilities shortens qualification and FDA approvals
- Technology leadership – HDI & miniaturization
- NextGen – 50% reduction in package size

Analyst Day 2026: Commercial Spotlight: Data Centers

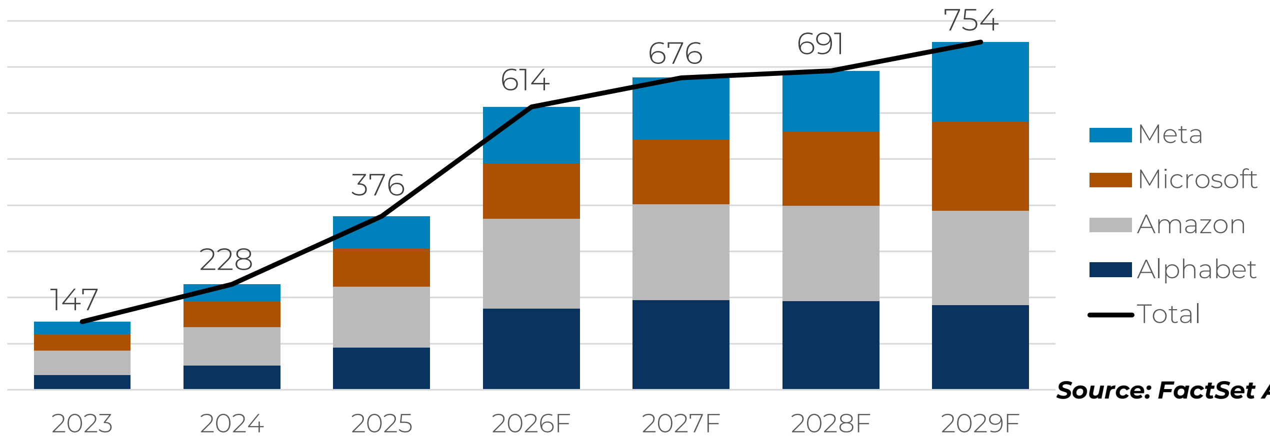
MAY 27, 2026

Rob Farrell

AI FUELS MASSIVE DATA CENTER BUILDOUT

UNIQUE OPPORTUNITY FOR TTM TECHNOLOGY LEADERSHIP & PROFITABLE GROWTH

Key CSPs Capex Investment Outlook ($B)



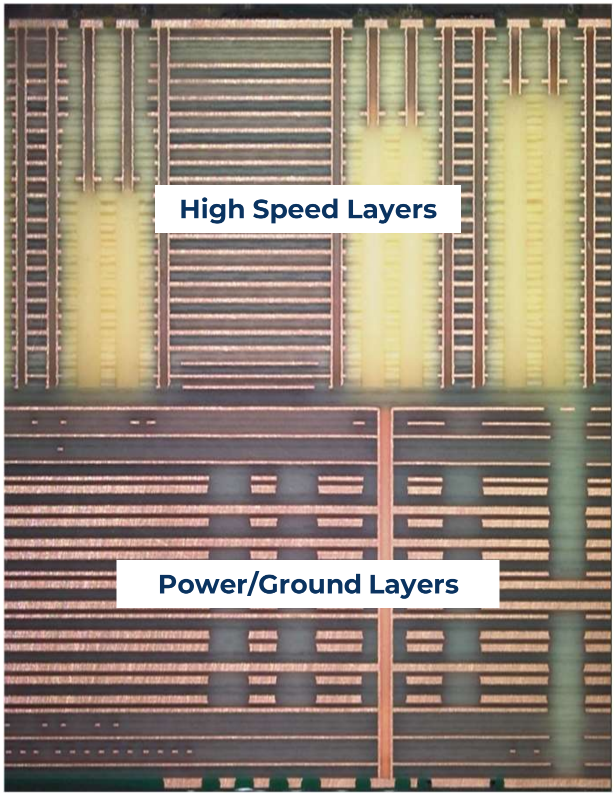
Source: FactSet Apr 26

AI Advanced Tech PCB forecasts surging:

- **N+M**
- **Advanced Tech High Layer PCBs**
- **Specialty Advanced Tech PCB products**

WHAT IS N+M TECHNOLOGY?

HYBRID ASYMMETRIC PCB ARCHITECTURE FOR OPTIMIZED SIGNAL INTEGRITY & POWER MANAGEMENT



- N+M Separates High Speed Signaling and Power/Ground into separate PCB Sub-sections
- N+M Improves Signal Integrity by isolating signal layers from power & ground layers
- N+M Improves Power Performance and Management
- TTM developed customer design guidelines for improved product quality, reliability and performance
- TTM engineered to meet demanding customer specifications for PCB flatness and BGA coplanarity

FOCUSED N+M GROWTH

TTM's PATH FOR AI DATA CENTER LEADERSHIP

Strategic Foundation Plants


Dongguan


Guangzhou

Strategic Supplemental Plants


Huiyang


Penang

Non-China Planned N+M Plants


Penang

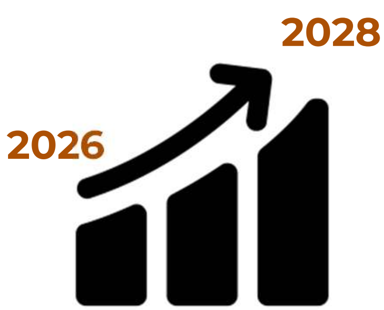

Eau Claire


Penang 2


Toronto

N+M

Growth Plan



- TTM developed N+M from customer product road mapping sessions
- TTM's Data Center growth strategy is built upon N+M Leadership
- Strategic capex investments support key customer program launches and production ramps

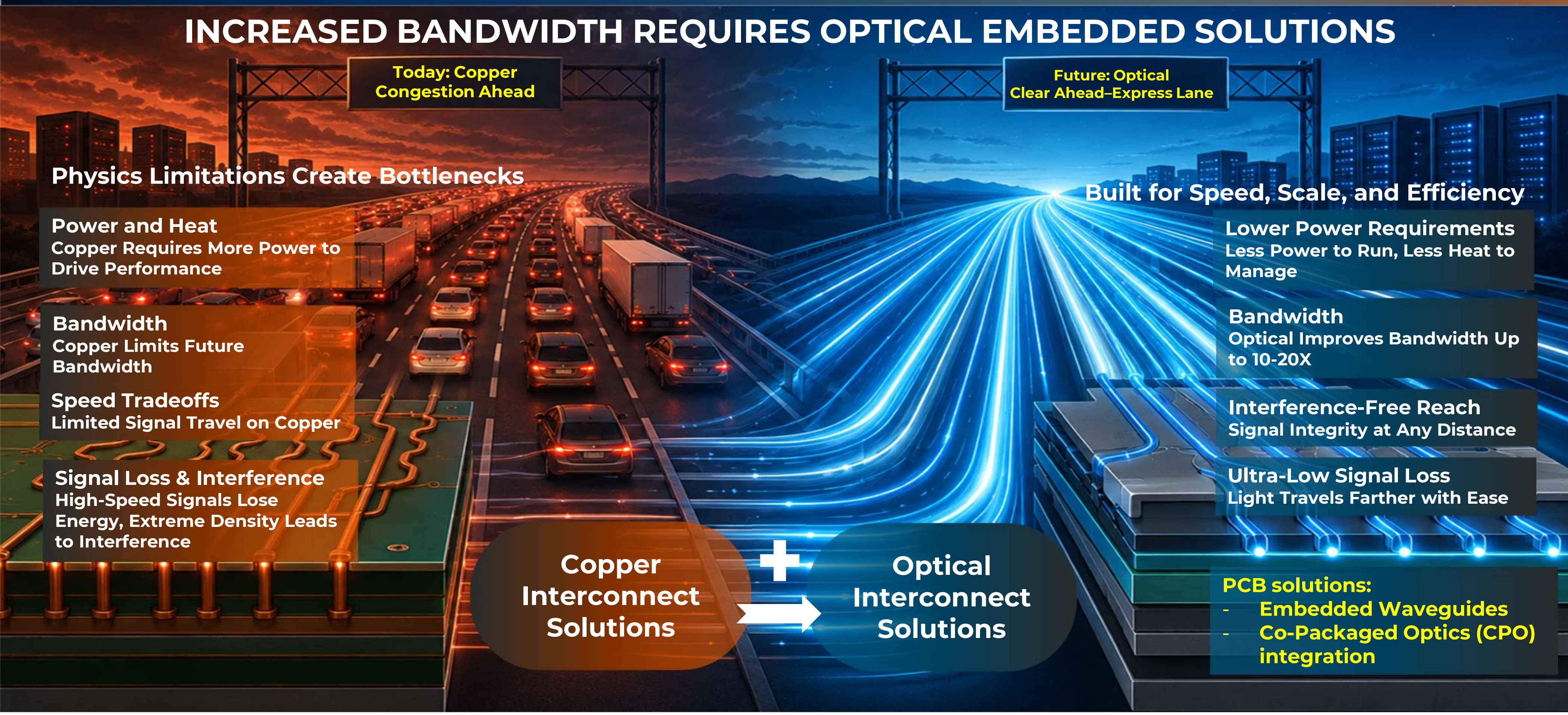
CASE STUDY: 1.6T SWITCH

TTM INNOVATION & OPS EXCELLENCE ENABLING NEXT GENERATION DATA CENTERS

- Early customer engagement identified N+M PCB technology as solution for Signal Integrity and Power Management challenges
- Executed extensive 1-year capex project to facilitate key customer's 1.6T Switch launch
  - Retooled & expanded GZ & DMC for multi-plant N+M capacity solution
- **N+M leadership for Data Center 1.6T+ switches and AI servers**
- **Up Next: Additional 1.6T and 3.2T Development**

1.6 AND 3.2 T AI SWITCHING

INCREASED BANDWIDTH REQUIRES OPTICAL EMBEDDED SOLUTIONS



Today: Copper
Congestion Ahead

Future: Optical
Clear Ahead–Express Lane

Physics Limitations Create Bottlenecks

Power and Heat
Copper Requires More Power to Drive Performance

Bandwidth
Copper Limits Future Bandwidth

Speed Tradeoffs
Limited Signal Travel on Copper

Signal Loss & Interference
High-Speed Signals Lose Energy, Extreme Density Leads to Interference

Built for Speed, Scale, and Efficiency

Lower Power Requirements
Less Power to Run, Less Heat to Manage

Bandwidth
Optical Improves Bandwidth Up to 10-20X

Interference-Free Reach
Signal Integrity at Any Distance

Ultra-Low Signal Loss
Light Travels Farther with Ease

Copper Interconnect Solutions + **Optical Interconnect Solutions**

PCB solutions:
- Embedded Waveguides
- Co-Packaged Optics (CPO) integration

COMMERCIAL SECTOR - WHY WE WIN

SUCCESSFUL EXECUTION NOW / READY FOR WHAT COMES NEXT

Focus
- Engaging Right Markets & Customers
- Investing for TTM Competitive Advantage
- Operational Excellence

Competitive Differentiation
- Targeted Technology Leadership
- Global Footprint Management
- Financial Strength

Speed & Execution
- New Technology & Product Development
- Appropriate Scale-up Solutions
- Capex to Revenue Conversion

Analyst Day 2026: Financial Viewpoints

MAY 27, 2026

Dan Boehle

FINANCIAL PRIORITIES

Revenue Growth

- Execution on current market demand opportunities leads to expected revenue of approximately $4 billion for 2026

Expand Profitability

- Gross Margin year-on-year expansion in 2026 expected to be driven by revenue mix, reduction of Penang headwind, and operational efficiencies
- 2026 year-on-year expansion of Operating Margin and EBITDA Margin expected through operating leverage and efficient cost management

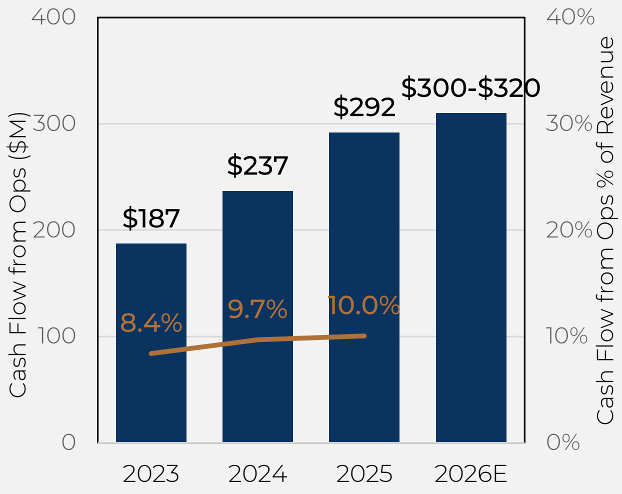
Cash Flow, Capital Structure, & Allocation Priorities

- Diligent working capital and operating cash flow management to enable Capital Expenditure requirements
- Focus spending on high-confidence internal growth investments and strategic M&A
- Maintain low debt leverage to optimize flexibility and liquidity

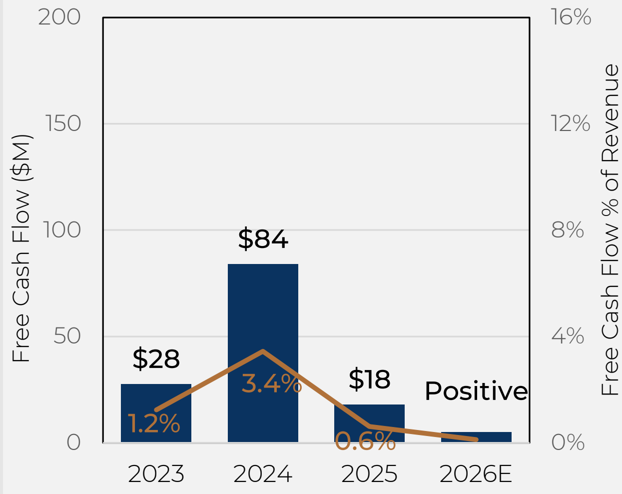
CASH FLOW

HEALTHY CASH FLOW FUNDS ORGANIC GROWTH

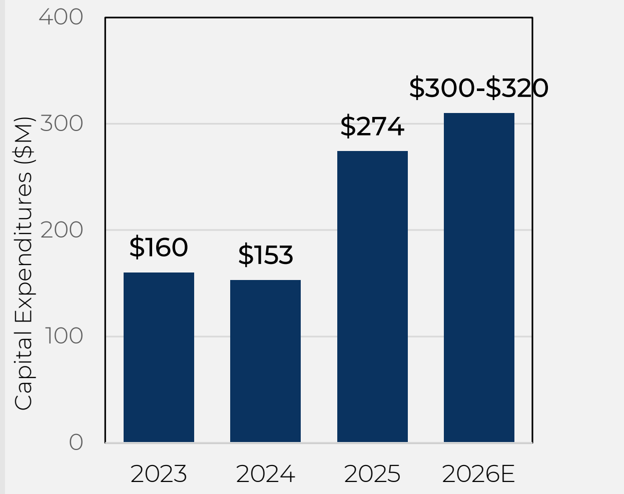
Cash Flows from Ops



Free Cash Flow



Net CapEx



Approved $120 $250 $150 $500+

EXPECTED CURRENT REFINANCING

$1.0 BILLION CASH FLOW REVOLVER AND UPSIZED $400 MILLION TLB PROJECTED TO PROVIDE INCREASED LIQUIDITY AND FINANCIAL FLEXIBILITY

Term loan B*

- We have taken steps to obtain commitments in respect of a repriced and upsized Term Loan B (TLB) due May 2030 in the aggregate principal amount of $400 million, which is expected to close in early June 2026
- If completed, the TLB is expected to be priced at SOFR+175 bps, a reduction of 50 bps from our current pricing
- The reduced pricing would provide significant expected cash interest savings for the remaining term

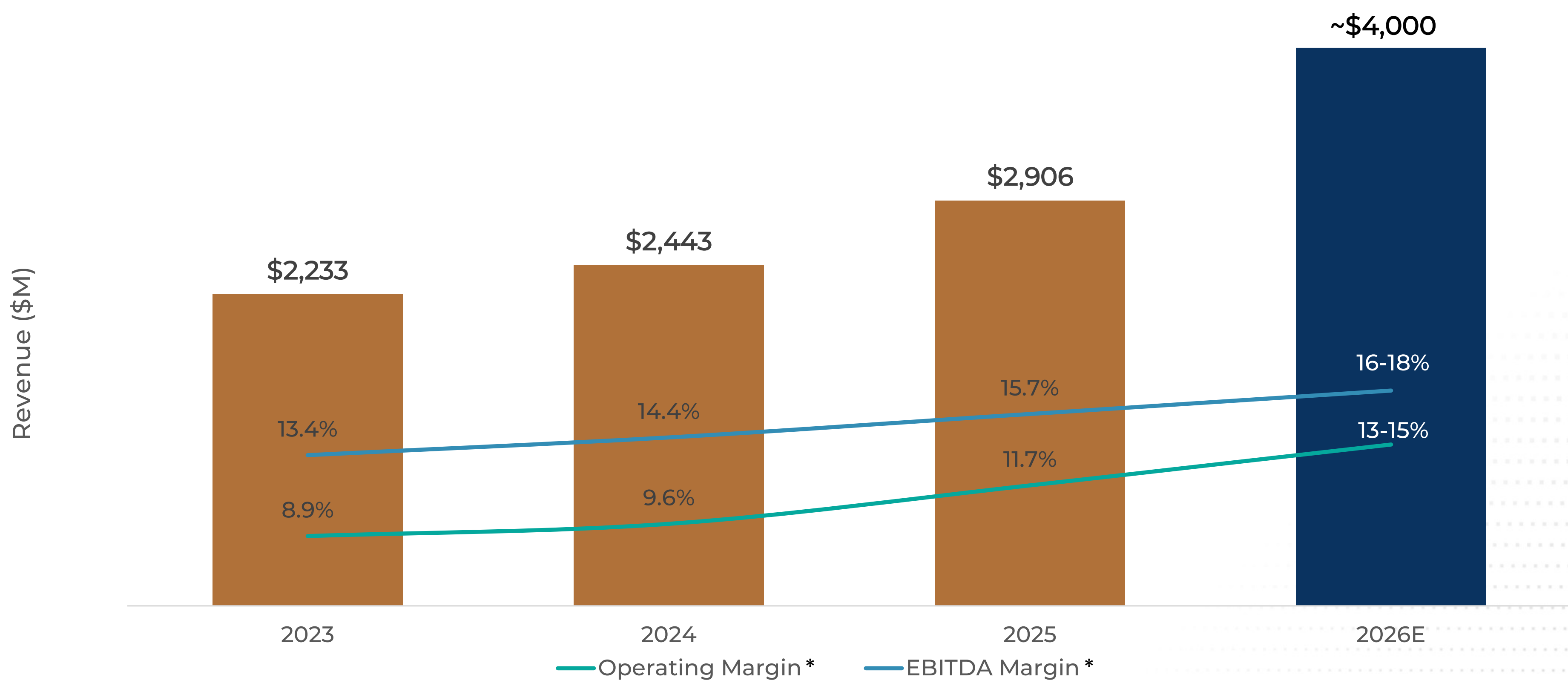
Cash flow revolver*

- Concurrent with the TLB refinancing, we have taken steps to obtain commitments for up to $1.0 billion cash flow revolver facility, maturing in 2031
- If completed, this revolver will replace our existing $150 million U.S. and $150 million Asia ABL facilities
- We expect to close this new revolver concurrent with the closing of the TLB refinancing in early June

**Subject to completion of definitive documentation and satisfaction of customary closing conditions*

REVENUE AND PROFIT

ACCELERATED REVENUE GROWTH & MARGIN EXPANSION



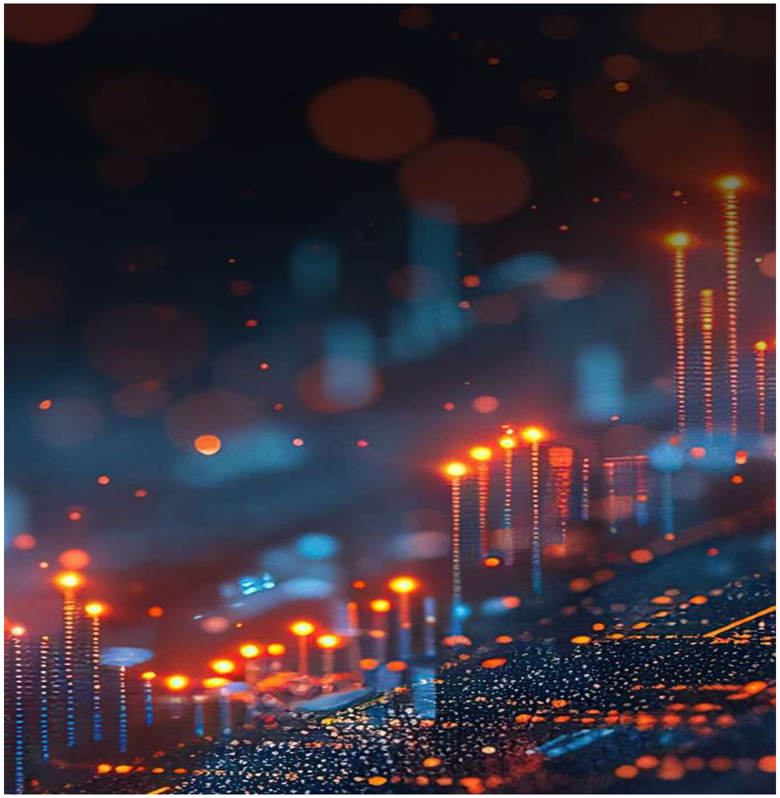
*Non-GAAP financial measure. See Appendix for reconciliation.

Analyst Day 2026: Closing Takeaways

MAY 27, 2026

Edwin Roks

CLOSING INVESTOR TAKEAWAYS



- **Evolving** from legacy PCBs to Advanced Interconnect & Integration
- **Vertically integrated**; creating "up the chain" solutions
- **Enabled** by technology leadership, early customer engagement
- **Megatrends** (AI & Defense) are behind ~80% of our growth momentum
- **Excel** in markets with high entry barriers
- **Strong** financial performance, with room to go

Analyst Day 2026

MAY 27, 2026

APPENDIX

APPENDIX

NON-GAAP RECONCILIATIONS (TTM CONSOLIDATED)

(In millions, except per share data)	2023	2024	2025
Non-GAAP operating income reconciliation:			
GAAP operating income	**$ 42.3**	**$ 116.0**	**$ 264.7**
Add back items:			
Amortization of definite-lived intangibles	61.6	44.9	36.9
Stock-based compensation	22.9	29.8	41.7
Gain on sale of property, plant and equipment	(0.2)	(15.7)	-
Unrealized (gain) loss on commodity hedge	(1.2)	0.4	(5.9)
Impairment, restructuring, acquisition-related and other charges	73.0	58.3	3.0
Non-GAAP operating income	**$ 198.4**	**$ 233.7**	**$ 340.4**
Non-GAAP operating margin	**8.9%**	**9.6%**	**11.7%**
Non-GAAP net income and EPS reconciliation:			
GAAP net income (loss)	**$ (18.7)**	**$ 56.3**	**$ 177.4**
GAAP earnings (loss) per diluted share	**$ (0.18)**	**$ 0.54**	**$ 1.68**
GAAP weighted-average diluted shares outstanding	**102.7**	**104.1**	**105.5**
Add back items:			
Amortization of definite-lived intangibles	61.6	44.9	36.9
Stock-based compensation	22.9	29.8	41.7
Non-cash interest expense	2.2	2.0	2.2
Gain on sale of property, plant and equipment	(0.2)	(15.7)	-
Unrealized (gain) loss on commodity hedge	(1.2)	0.4	(5.9)
Unrealized (gain) loss on foreign exchange	1.0	(1.0)	14.6
Impairment, restructuring, acquisition-related and other charges	72.9	58.3	3.0
Income taxes	(0.0)	2.5	(11.0)
Non-GAAP net Income	**$ 140.4**	**$ 177.5**	**$ 259.0**
Non-GAAP earnings per diluted share	**$ 1.34**	**$ 1.70**	**$ 2.46**
Non-GAAP weighted-average diluted shares outstanding	**104.6**	**104.1**	**105.5**
Adjusted EBITDA reconciliation:			
GAAP net income (loss)	**$ (18.7)**	**$ 56.3**	**$ 177.4**
Add back items:			
Income tax provision	19.0	27.7	32.9
Interest expense	48.1	47.5	45.3
Amortization of definite-lived intangibles	61.6	44.9	36.9
Depreciation expense	99.2	105.2	110.3
Stock-based compensation	22.9	29.8	41.7
Gain on sale of property, plant and equipment	(0.2)	(15.7)	-
Unrealized (gain) loss on commodity hedge	(1.2)	0.4	(5.9)
Unrealized (gain) loss on foreign exchange	1.0	(1.0)	14.6
Impairment, restructuring, acquisition-related and other charges	67.5	56.4	3.0
Adjusted EBITDA	**$ 299.2**	**$ 351.5**	**$ 456.3**
Adjusted EBITDA margin	**13.4%**	**14.4%**	**15.7%**